TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS

TIDA-00456

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C7, C8	3	4.7uF	GRM188R61A475ME15	MuRata	CAP, CERM, 4.7 µF, 10 V,	0603
2	C2	1	0.1uF	VJ1812Y104KXEAT5Z	Vishay-Vitramon	CAP, CERM, 0.1 µF, 500	1812
3	C3, C4	2	100pF	GRM033R71C101KA01D	MuRata	CAP, CERM, 100 pF, 16 V, +/- 10%, X7R, 0201	0201
4	C5	1	1000pF	885012206034	Wurth Elektronik	CAP, CERM, 1000 pF, 16 V, +/- 10%, X7R, 0603	0603
5	C6	1	10pF	C0805C100J5GACTU	Kemet	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
6	D1	1	10V	MMSZ5240B-7-F	Diodes Inc.	Diode, Zener, 10 V, 500	SOD-123
7	D2, D3, D4	3	40V	BAS40-7-F	Diodes Inc.	Diode, Schottky, 40 V, 0.2	SOT-23
8	J1, J2	2		SPC15354	Tenma	BANANA JACK, SOLDER	Black Insulated Banana
9	J3	1		TSW-102-07-G-S	Samtec	Header, 100mil, 2x1,	2x1 Header
10	J4, J5	2		SPC15363	Tenma	BANANA JACK, SOLDER LUG, RED, TH	Red Insulated Banana Jack
11	J6, J7	2		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1,	3x1 Header
12	J8	1		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1,	4x1 Header
13	Q1	1		STR2550	Used in BOM report	Transistor, NPN, xxV, xA, [PackageReference]	Used in PnP output and some BOM reports
14	Q2	1		MMBT3904	Used in BOM report	Transistor, NPN, xxV, xA, [PackageReference]	Used in PnP output and some BOM reports
15	R1	1	0.01	PMR50HZPFU10L0	Rohm	RES, 0.01, 1%, 1 W, 2010	2010
16	R2, R3	2	100k	CRCW0805100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.125 W, 0805	0805
17	R4, R8, R10, R11	4	10.0k	RT0805BRD0710KL	Yageo America	RES, 10.0 k, 0.1%, 0.125 W, 0805	0805
18	R5	1	1.00k	ERJ-P06F1001V	Panasonic	RES, 1.00 k, 1%, 0.25 W, 0805	0805

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19	R6	1	402k	ERJ-8ENF4023V	Panasonic	RES, 402 k, 1%, 0.25 W, 1206	1206
20	R7	1	49.9k	RG2012P-4992-B-T5	Susumu Co Ltd	RES, 49.9 k, 0.1%, 0.125 W, 0805	0805
21	R9	1	988k	RT0805BRD07988KL	Yageo America	RES, 988 k, 0.1%, 0.125	0805
22	R12, R13, R17	3	2.2k	CRCW08052K20JNEA	Vishay-Dale	RES, 2.2 k, 5%, 0.125 W,	0805
23	R14	1	1.45k	RT0805BRD071K45L	Yageo America	RES, 1.45 k, 0.1%, 0.125	0805
24	R15	1	2.49k	CRCW08052K49FKEA	Vishay-Dale	RES, 2.49 k, 1%, 0.125 W,	0805
25	R16	1	3.12k	RT0805BRD073K12L	Yageo America	RES, 3.12 k, 0.1%, 0.125	0805
26	R18	1	84.5	CRCW080584R5FKEA	Vishay-Dale	RES, 84.5, 1%, 0.125 W,	0805
27	R19	1	374	CRCW0805374RFKEA	Vishay-Dale	RES, 374, 1%, 0.125 W, 0	0805
28	TP1	1	Black	5001	Keystone	Test Point, Miniature, Blac	Black Miniature Testpoint
29	TP2, TP3	2	White	5002	Keystone	Test Point, Miniature, Whi	White Miniature Testpoint
30	U1	1		INA138QPWRQ1	Used in BOM report		eg: 0603, used in PnP report
31	U2	1		TLC2272AQDRG4Q1A	Texas Instruments	Automotive Catalog Advar	D0008A
32	U3	1		ADS1115QDGSRQ1	Texas Instruments	Ultra-Small, Low-Power, 1	DGS0010A
33	U4	1		ISO7241CQDWRQ1	Texas Instruments	25 Mbps Automotive Catal	DW0016A

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